

(11) Publication number:

05062911 A

PATENT ABSTRACTS OF JAPAN

Generated Document

(21) Application number: 03223234

(51) Intl. Cl.: H01L 21/205 H01S 3/18

(22) Application date: 04.09.91

(30) Priority:(43) Date of application publication:12.03.93

publication:
(84) Designated contracting

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(54) MANUFACTURE OF SEMICONDUCTOR SUPERLATTICE

(57) Abstract:

PURPOSE: To form a Ge layer and an Si layer or a Ge-Si layer and an Si layer or a Ge-Si layer and an Si layer on an Si substrate, and also to put a hetero-epitaxial growth method, in which excellent crystal quality and high growth speed can be obtained, into practical use.

CONSTITUTION: The title semiconductor superlattice

manufacturing method is the method with which a Ge layer and an Si layer or Ge-Si layer and an Si layer are epitaxially grown on an Si substrate by conducting a depressed CVD method under the amosphere containing oxidizing impurity gas of 1000ppb or lower using GeH4 and trisilanc (SiJH3) as raw gas and also using H2 or inert gas as carrier gas.

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